1. (Previously Presented) An apparatus for separating interconnects comprising:

partial-circle structures; and

temperature-sensitive releases in contact with said partial-circle structures,

wherein said partial-circle structure is positioned to separate said interconnects when released by said temperature-sensitive release, and wherein rotational paths of said partial-circle structures partially overlap.

2. (Original) The apparatus in claim 1, wherein said at least one partial-circle structure comprises a plurality of partial-circle structures in contact with a plurality of temperature-sensitive releases, and

each of said temperature-sensitive releases are different, such that each of said partial-circle structures is released at a different temperature.

3. (Currently Amended) The apparatus in claim 1, wherein said at least one partial-circle structure comprises a plurality of partial-circle structures in contact with a plurality of temperature-sensitive releases~~, and~~

~~wherein rotational paths of said partial-circle structures partially overlap~~.

4. (Original) The apparatus in claim 1, wherein said at least one partial-circle structure comprises a plurality of partial-circle structures in contact with a plurality of temperature-sensitive releases, and

wherein a workpiece is positioned between said partial-circle structures.

5. (Original) The apparatus in claim 4, wherein said partial-circle structures rotate around axis external to said workpiece.

6. (Original) The apparatus in claim 4, wherein said partial-circle structures pass between two parts of said workpiece when released by said temperature-sensitive release, and said partial-circle structures break interconnects between said parts of said workpiece when released by said temperature-sensitive release.

7. (Original) The apparatus in claim 1, wherein said temperature-sensitive release is adapted to release said partial-circle structure at a temperature above a melting point of said interconnects.

8. (Previously Presented) An apparatus for separating interconnects comprising:

partial-circle structures;

temperature-sensitive releases in contact with said partial-circle structures, wherein said partial-circle structures are positioned to separate said interconnects when released by said temperature-sensitive releases; and

reservoirs positioned to receive material from said interconnects separated by said partial-circle structures,

wherein rotational paths of said partial-circle structures partially overlap.

9. (Original) The apparatus in claim 8, wherein each of said temperature-sensitive releases

are different, such that each of said partial-circle structures is released at a different temperature.

10. (Cancelled).

11. (Original) The apparatus in claim 8, wherein a workpiece is positioned between said partial-circle structures.

12. (Original) The apparatus in claim 11, wherein said partial-circle structures rotate around axis external to said workpiece.

13. (Original) The apparatus in claim 11, wherein said partial-circle structures pass between two parts of said workpiece when released by said temperature-sensitive releases, and said partial-circle structures break interconnects between said parts of said workpiece when released by said temperature-sensitive releases.

14. (Original) The apparatus in claim 8, wherein said temperature-sensitive releases are adapted to release said partial-circle structures at temperatures above a melting point of said interconnects.

15. (Previously Presented) An apparatus for separating interconnects comprising:

rotationally biased partial-circle structures; and

temperature-sensitive releases in contact with said partial-circle structures, wherein said partial-circle structures are positioned to rotate and separate said interconnects when released by said temperature-sensitive releases and wherein rotational paths of said partial-circle structures partially overlap.

16. (Original) The apparatus in claim 15, wherein each of said temperature-sensitive releases are different, such that each of said partial-circle structures is released at a different temperature.

17. (Cancelled).

18. (Original) The apparatus in claim 15, wherein a workpiece is positioned between said partial-circle structures.

19. (Original) The apparatus in claim 18, wherein said partial-circle structures rotate around axis external to said workpiece.

20. (Original) The apparatus in claim 18, wherein said partial-circle structures pass between two parts of said workpiece when released by said temperature-sensitive releases, and said partial-circle structures break interconnects between said parts of said workpiece when released by said temperature-sensitive releases.